

-60V P-Channel Enhancement Mode MOSFET

Description

The AP3P06LI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = -60V I_D =-3.8A

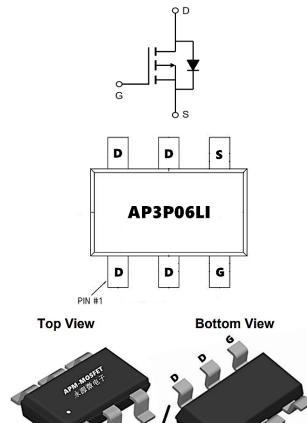
 $R_{DS(ON)} < -150 m\Omega @ V_{GS} = -10V$ (Type: 125m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)	
AP3P06LI	SOT23-6L	AP3P06LI	3000	

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	-60	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.8	A
I₀@T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-2.4	A
Ідм	Pulsed Drain Current ²	-12	A
P _D @T _A =25°C	Total Power Dissipation ³	1.5	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-Ambient ¹	125	°C/W
Rejc	Thermal Resistance Junction-Case ¹	80	°C/W

永源微電子科技有限公司



-60V P-Channel Enhancement Mode MOSFET

Electrical Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V_{GS} =0V , I _D =-250uA	-60	-67		V	
$\triangle BV$ DSS/ $\triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to 25° C , I _D =-1mA		-0.021		V/℃	
_		V _{GS} =-10V , I _D =-1.5A		125	150		
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-1A		158	200	mΩ	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	1.7	-2.5	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID2000A		4.08		mV/℃	
Ipss	Drain-Source Leakage Current	$V_{\text{DS}}\text{=-}48\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}25^\circ\!\mathbb{C}$			1	uA	
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}\text{=-48V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}55^\circ\!\!\mathrm{C}$			5		
lgss	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-1.5A		5.9		S	
Qg	Total Gate Charge (-4.5V)			4.6			
Qgs	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-4.5V , I _D =- 1.5A		1.4		nC	
Qgd	Gate-Drain Charge	1.07		1.62			
Td(on)	Turn-On Delay Time			17.4			
Tr	Rise Time	V _{DS} =-15V , V _{GS} =-10V , R _G =3.3 Ω,		5.4			
Td(off)	Turn-Off Delay Time	I _D =-1A		37.2		ns	
Tf	Fall Time			2.4			
Ciss	Input Capacitance			531			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		59		pF	
Crss	Reverse Transfer Capacitance			38			
ls	Continuous Source Current ^{1,4}				-1.7	Α	
lsм	Pulsed Source Current ^{2,4}	$V_G=V_D=0V$, Force Current			-7	Α	
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , TJ=25℃			-1.2	V	

Note :

 $1_{\mbox{\tiny V}}$ The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

 $3\$ The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ junction temperature

4. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

N



-60V P-Channel Enhancement Mode MOSFET

P-Channel Typical Characteristics

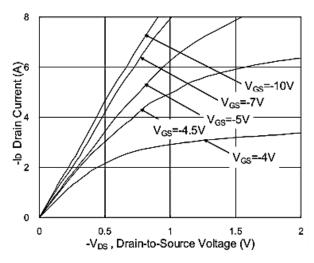


Fig.1 Typical Output Characteristics

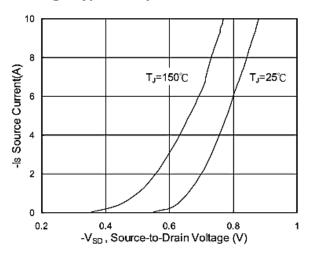
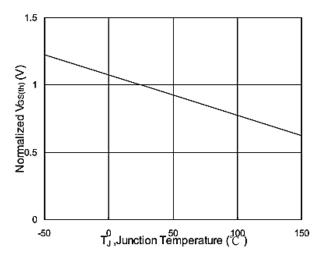
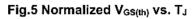


Fig.3 Forward Characteristics Of Reverse





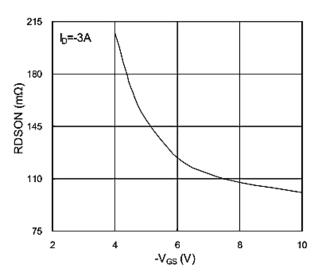


Fig.2 On-Resistance vs. G-S Voltage

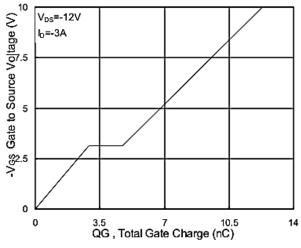


Fig.4 Gate-Charge Characteristics

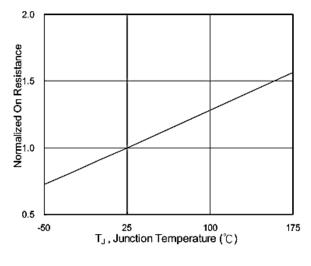


Fig.6 Normalized RDSON vs. TJ

ω



-60V P-Channel Enhancement Mode MOSFET

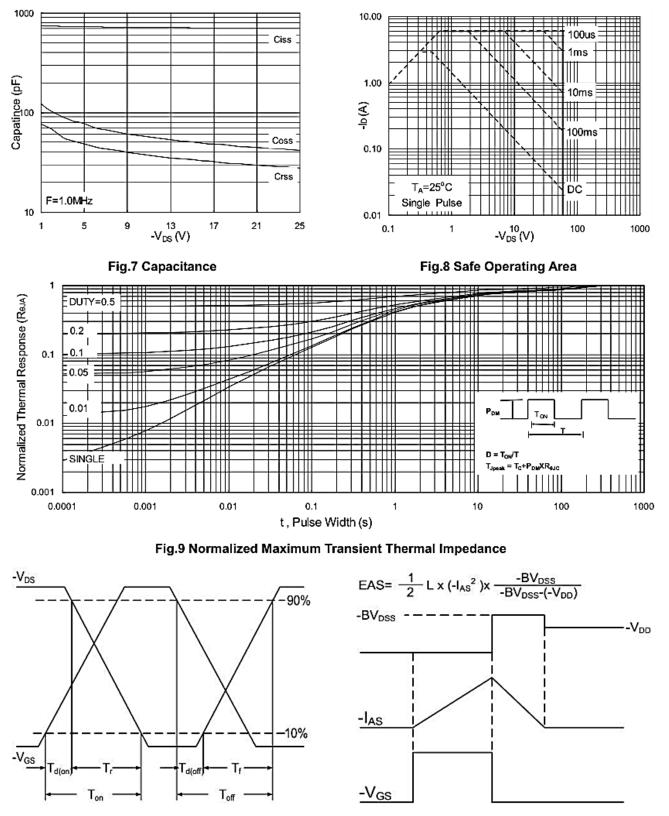


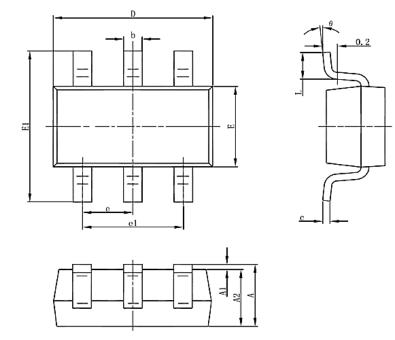
Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform



-60V P-Channel Enhancement Mode MOSFET

Package Mechanical Data-SOT23-6-Single



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950 (BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0	8	0	8	

С

-60V P-Channel Enhancement Mode MOSFET

Attention

1,Any and all APM Microelectronics products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your APM Microelectronics representative nearest you before using any APM Microelectronics products described or contained herein in such applications.

2,APM Microelectronics assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all APM Microelectronics products described or contained herein.

3, Specifications of any and all APM Microelectronics products described or contained here instipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

4, APM Microelectronics Semiconductor CO., LTD. strives to supply high quality high reliabilityproducts. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. Whendesigning equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

5, In the event that any or all APM Microelectronics products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of APM Microelectronics Semiconductor CO., LTD.

7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. APM Microelectronics believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "DeliverySpecification" for the APM Microelectronics product that you Intend to use.

ന



-60V P-Channel Enhancement Mode MOSFET

Edition	Date	Change
RVE1.0	2021/3/1 Initial relea	

Copyright Attribution"APM-Microelectronice"

-